

# STM32WL\_QFN48\_HP\_DirectTie\_RefBoard

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MB1789\_HP

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## Table of contents

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Sheet 1: Project overview (this page)

Sheet 2: MB1789\_HPP.SchDoc

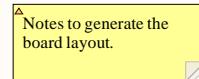
## Legend

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General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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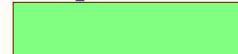
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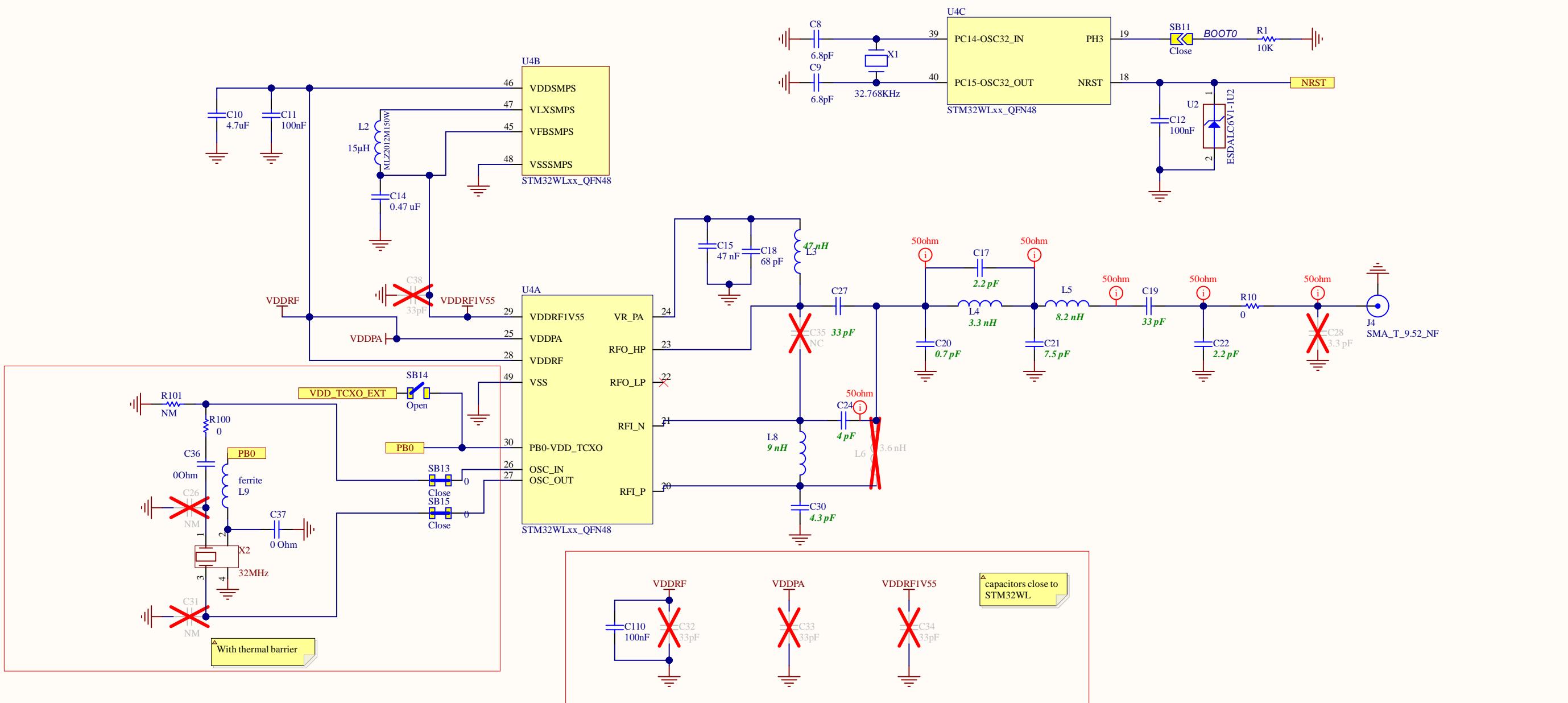
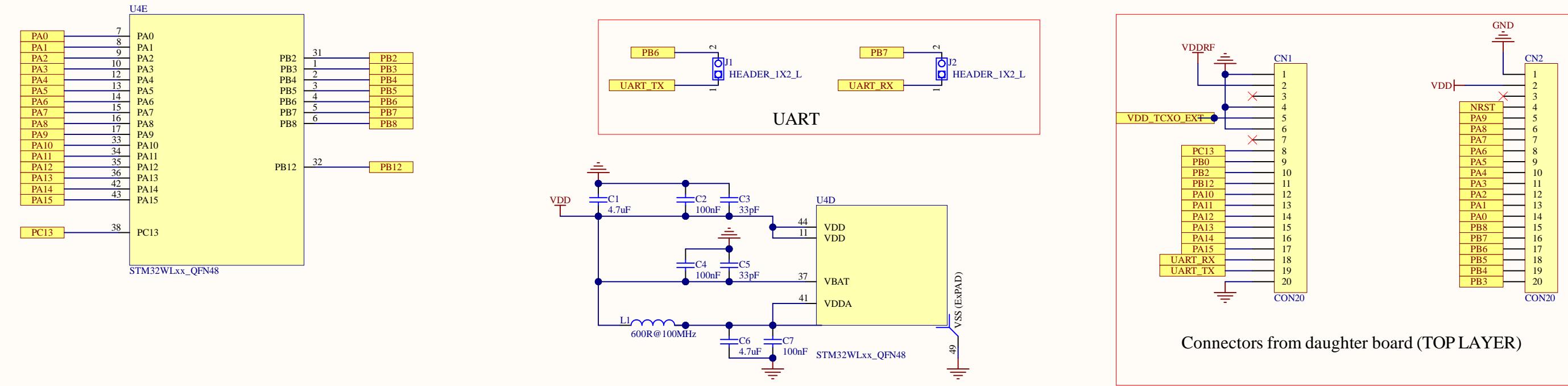
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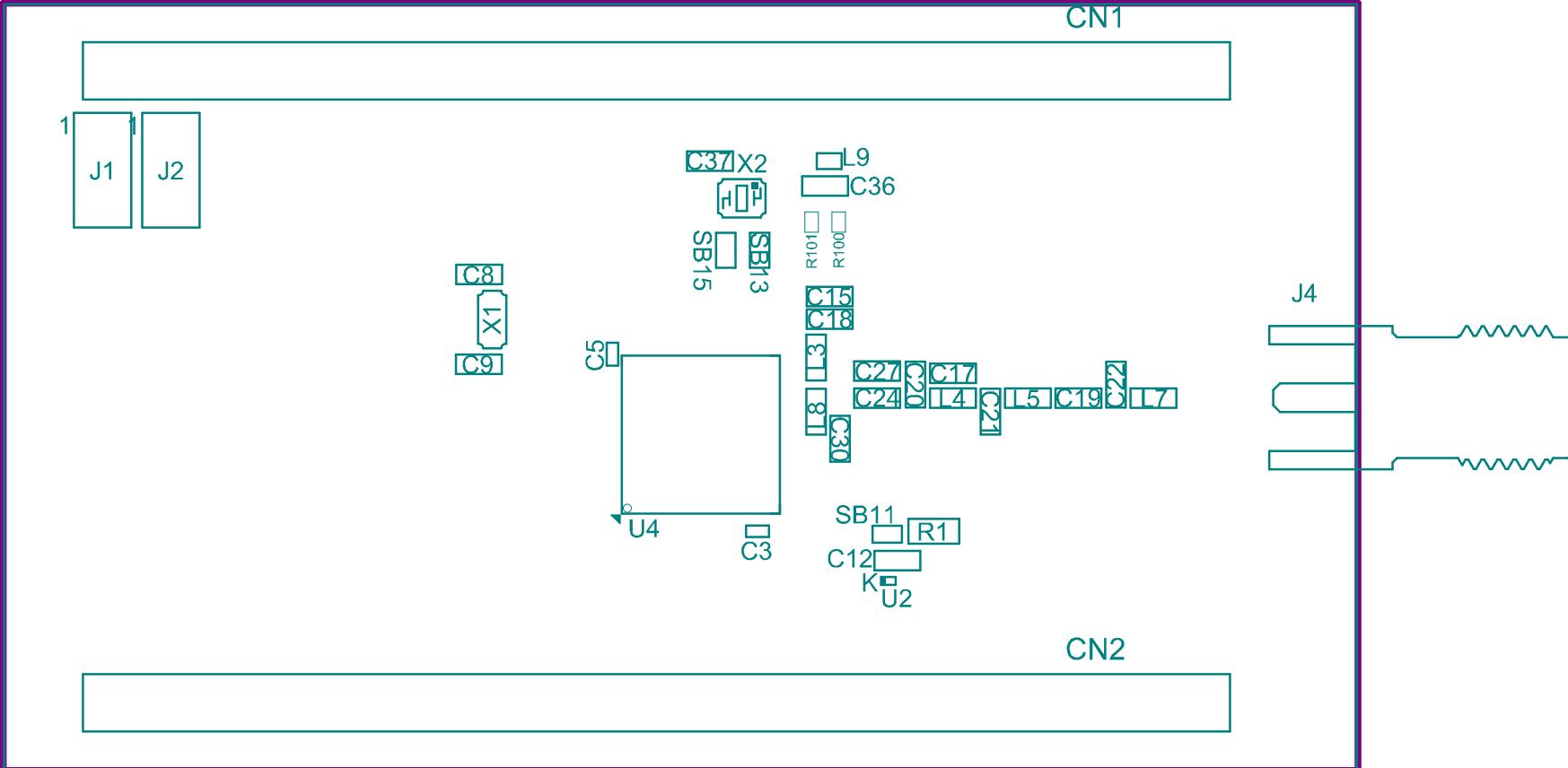
U\_Top  
MB1789\_HPP.SchDoc



Title: Schematic sheet title to update		
Project: STM32WL_QFN48_HP_DirectTie_RefBoard		
Variant: HighBand_HighPower		
Revision: A-01	Reference: MB1789_HPP	
Size: A4	Date: 04-04-2022	Sheet: 1 of 2







Project: STM32WL\_QFN48\_HP\_DirectTie\_RefBoard

Layer: Top Assembly

Gerber: .GM14

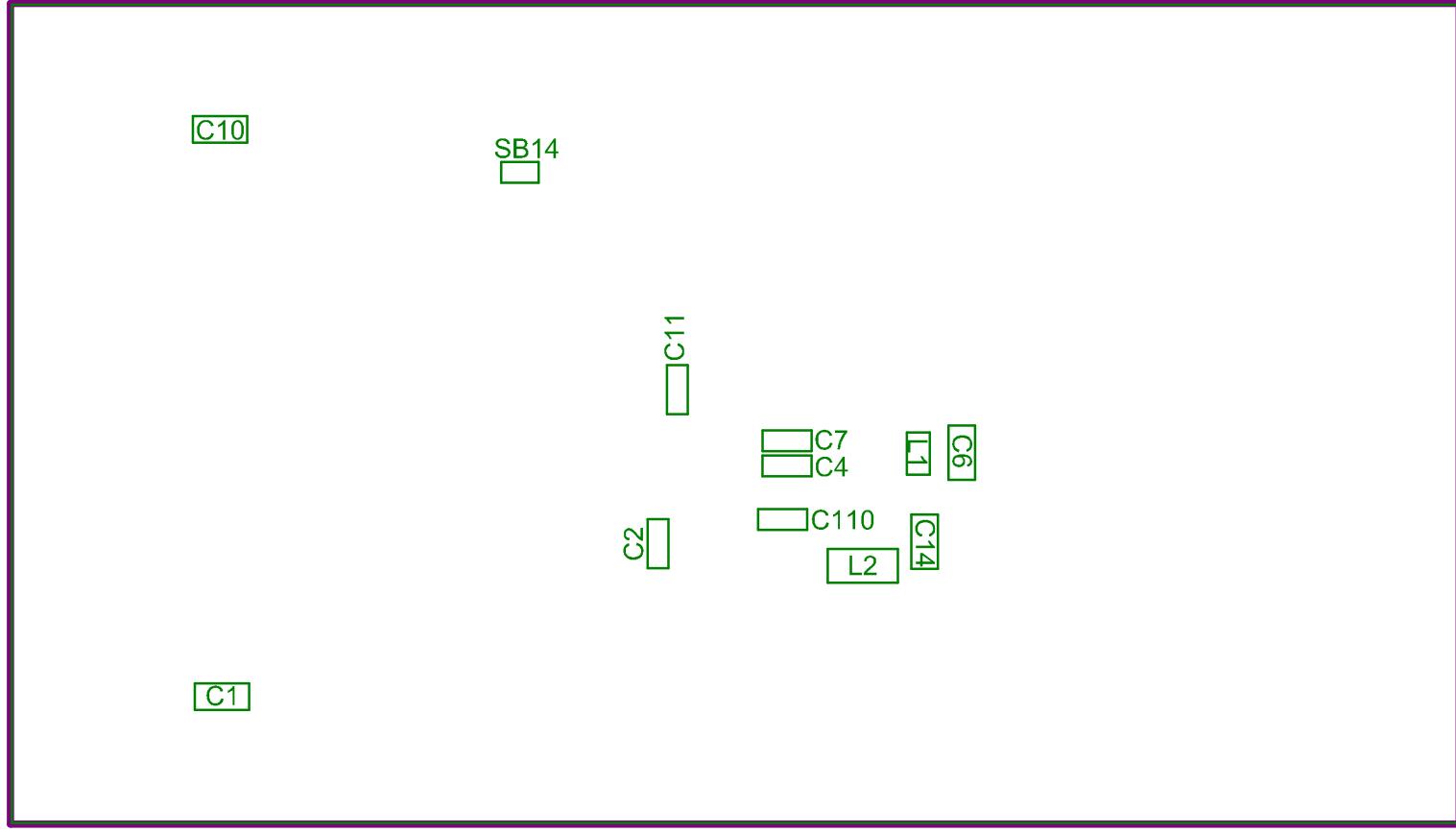
Variant: HighBand\_HighPower

Ref: MB1789\_HP

Date: 04-04-2022

Rev: A





Project: STM32WL\_QFN48\_HP\_DirectTie\_RefBoard

Layer: Bottom Assembly

Gerber:.GM15

Variant: HighBand\_HighPower

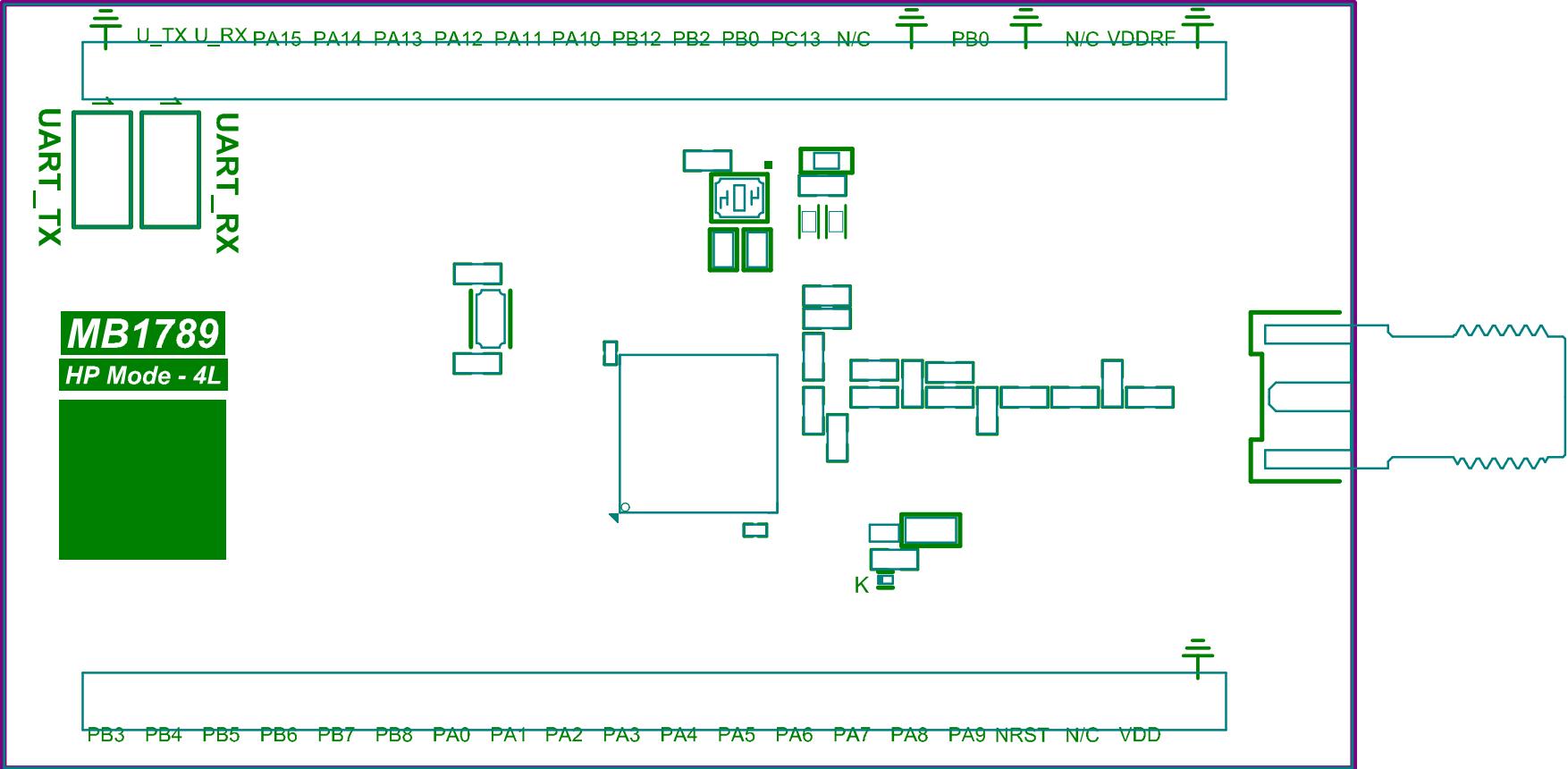
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Date: 04-04-2022

Rev: A



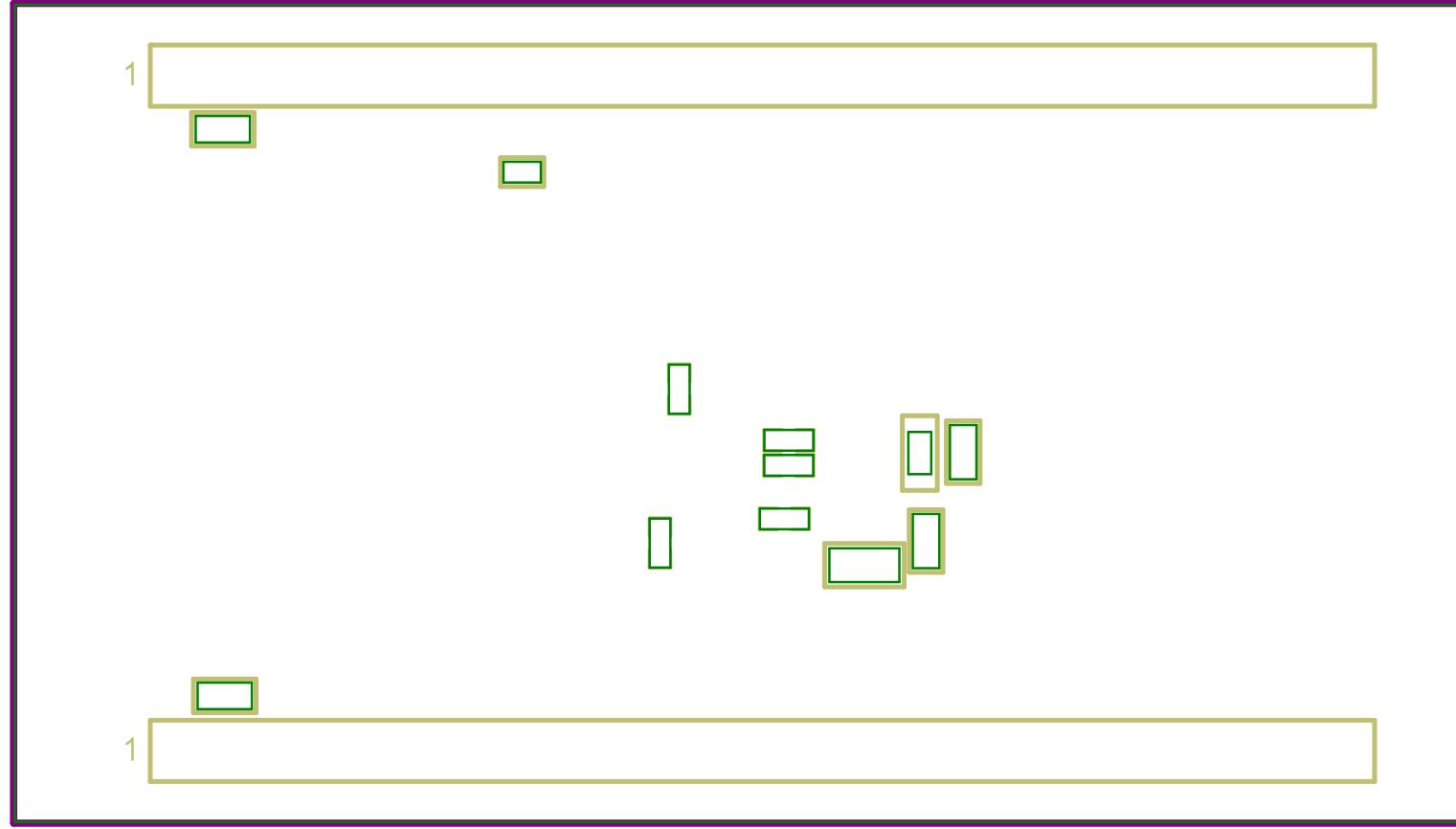




Top Overlay

.GTO

Bottom Overlay



.GBO